features

- 10-Bit, 25-MSPS, Analog-to-Digital Converter (ADC)
- Single Power Supply Operation, 2.7 V to 3.3 V
- Low Power: 95 mW at 2.7 V, Power-Down Mode: 1 mW
- Full-Channel Differential-Nonlinearity Error:
 ±0.5 LSB Typical
- Full-Channel Integral-Nonlinearity Error:
 ±1.5 LSB Typical
- Dual Input Modes: CCD and Video
- Programmable-Gain Amplifier (PGA) With 0-dB to 36-dB Gain Range (0.047 dB/Step) for CCD Mode, 0-dB to 12-dB Gain Range (0.047 dB/Step) for Video Mode

- Serial Interface for Register Configuration
- Programmable Black-Level and Offset Calibration
- Analog Gain Implementation With Specified No Missing Code, Even At High Gains
- Additional Digital-to-Analog Converters (DACs) for External Analog Setting
- Internal Reference Voltages
- Programmable Internal-Timing Signal Delays
- 48-Terminal TQFP Package

applications

- Digital Still Camera
- Digital Camcorder
- Digital Video Camera

description

The VSP1021 device is a highly-integrated monolithic analog-signal processor/digitizer designed to interface the area charge-coupled-device (CCD) sensors in digital-camera and camcorder applications. The VSP1021 device performs all the analog processing functions necessary to maximize the dynamic range, corrects various errors associated with the CCD sensor, and then digitizes the results with an on-chip, high-speed ADC. The key components of the VSP1021 device include:

- Input clamp circuitry and a correlated double sampler (CDS)
- Programmable-gain amplifier (PGA) with 0-dB to 36-dB gain range for CCD mode and 0-dB to 12-dB range for video mode
- Two internal DACs for automatic or programmable optical-black-level and offset calibration
- 10-bit, 25-MSPS pipeline ADC for CCD mode and a 28-MSPS ADC for video mode
- Parallel data port for easy microprocessor interface and a serial port for configuring internal control registers
- Two additional DACs for external system control
- Internal reference voltages

The VSP1021 device is designed using advanced CMOS process and operates from a single 3-V power supply with a normal power consumption of just 95 mW, and 1 mW in power-down mode.

High throughput rate, single 3-V operation, very-low-power consumption, and fully-integrated analog-processing circuitry make the VSP1021 device an ideal CCD and video-signal-processing solution for electronic video-camcorder applications.

This device is available in a 48-terminal TQFP package and is specified over an operating temperature range of –20°C to 75°C.

AVAILABLE OPTIONS

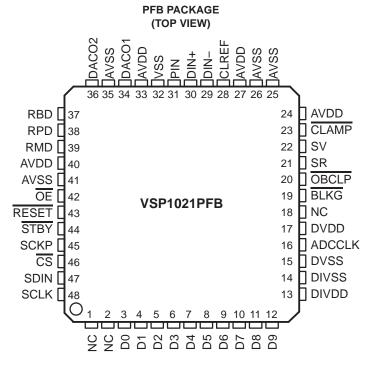
TA	PACKAGE TQFP (PFB)
−20°C to 75°C	VSP1021PFB



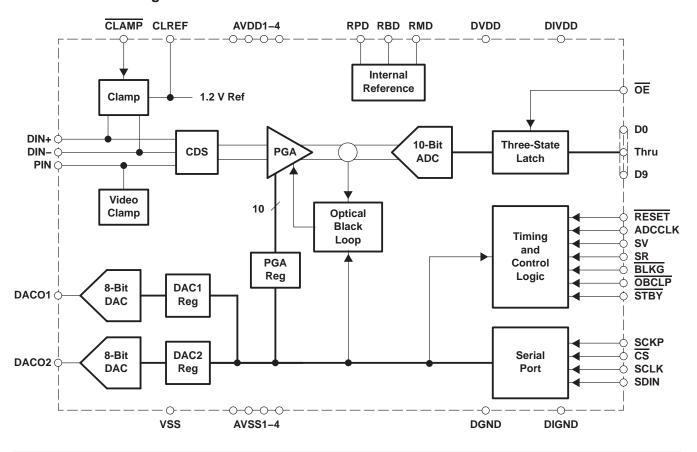
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



terminal assignments



functional block diagram





Terminal Functions

TERMINAL			
NAME	NUMBER	TYPE	DESCRIPTION
ADCCLK	16	ı	ADC clock input
AVDD	24, 27, 33, 40		Analog-supply voltage, 3 V
AVSS	25, 26, 35, 41		Analog ground
BLKG	19	I	Control input. The CDS operation is disabled when BLKG is pulled low.
CLAMP	23	I	CCD signal clamp-control input
CLREF	28	0	Clamp reference-voltage output
CS	46	ı	Chip select. A logic low on this input enables the VSP1021 serial port.
DACO1	34	0	Digital-to-analog converter output 1
DACO2	36	0	Digital-to-analog converter output 2
DIN-	29	I	Negative input signal from CCD
DIN+	30	I	Positive input signal from CCD
DIVDD	13		Digital-interface-circuit supply voltage, 1.8 V to 3.6 V
DIVSS	14		Digital-interface-circuit ground
DVSS	15		Digital ground
DVDD	17		Digital-supply voltage, 3 V
D0-D9	3–12	0	10-bit, 3-state ADC output data or offset DACs test data
NC	1, 2, 18		Not connected
OBCLP	20	I	Optical black-level and offset-calibration-control input, active low
ŌĒ	42	I	Output data enable, active low
PIN	31	I	Video-input signal
RBD	37	0	Internal bandgap reference for external decoupling
RESET	43	I	Hardware reset input, active low. This signal forces a reset of all internal registers.
RMD	39	0	Ref– output for external decoupling
RPD	38	0	Ref+ output for external decoupling
SCKP	45	I	This terminal selects the polarity of SCLK. 0 = SCLK stays high during idle period. The serial data is latched at the rising edge of SCLK. 1 = SCLK stays low during idle period. The serial data is latched at the falling edge of SCLK.
SCLK	48	I	Serial clock input. This clock synchronizes the serial-data transfer.
SDIN	47	I	Serial data input to configure the internal registers
SR	21	I	CCD reference-level sample-clock input
STBY	44	I	Hardware power-down control input, active low
SV	22	I	CCD signal-level sample-clock input
VSS	32		Analog ground



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, AVDD, DVDD, DIVDD	0.3 V to 6.5 V
Analog input voltage range	0.3 V to AVDD+0.3 V
Digital input voltage range	0.3 V to DVDD+0.3 V
Operating virtual junction temperature range, T _J	–40°C to 125°C
Operating free-air temperature range, T _A	–20°C to 75°C
Storage temperature range, T _{stq}	–65°C to 150°C
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

power supplies

PARAMETER	MIN	NOM	MAX	UNIT
Analog supply voltage, AVDD	2.7	3	3.3	V
Digital supply voltage, DVDD	2.7	3	3.3	V
Digital-interface supply voltage, DIVDD	1.8		3.6	V

digital inputs

PARAMETER	TEST CONDITIONS	MIN	NOM MAX	UNIT	
High-level input voltage, V _{IH}		0.8 DVDD		V	
Low-level input voltage, V _{IL}			0.2 DVDD	V	
Input ADCCLK frequency			25 (CCD)	T	
			28 (Video)	MHz	
		20 (CCD)			
ADCCLK pulse duration, clock high, $t_{W(MCLKH)}$	DVDD = 3 V	17.9 (Video)		ns	
4P001K		20 (CCD)		Τ	
ADCCLK pulse duration, clock low, $t_{W(MCLKL)}$		17.9 (Video)		ns	
Input SCLK frequency			40	MHz	
SCLK pulse duration, clock high, t _W (SCLKH)		12.5		ns	
SCLK pulse duration, clock low, t _W (SCLKL)		12.5		ns	



electrical characteristics over recommended operating free-air temperature range, T_A = 25°C, AVDD = DVDD = 3 V, ADCCLK = 25 MHz (unless otherwise noted)

total device

PARAMETER	TEST CONDITIONS	MIN TYP	MAX	UNIT
Device power consumption	AVDD = DVDD = 3 V	105		mW
Device power consumption	AVDD = DVDD = 2.7 V	95		mW
Power consumption in power-down mode		1		mW
Full-scale input span		1		V _{p-p}
Full-channel nonlinearity		0.5	1	LSB
No missing code		Assured		

analog-to-digital converter (ADC)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
	ADO mandatan			10 (CCD)		D:1-	
	ADC resolution			8 (Video)		Bits	
INL	Integral nonlinearity	AVDD DVDD 0.7.V4-2.2.V		±1.2		I CD	
DNL	Differential nonlinearity	AVDD=DVDD= 2.7 V to 3.3 V		±0.5	±0.99	LSB	
	Company in a mate				25 (CCD)	N 41 1-	
	Conversion rate				28 (Video)	MHz	
	ADC output latency			5		CLK cycles	
SNR	Input-referred signal-to-noise ratio	0-dB gain	65			dB	
SINIX	input-relened signal-to-noise ratio	36-dB gain		78		uБ	

correlated double sampler(CDS) and programmable-gain amplifier (PGA)

PARA	METER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
000 and 004 accord	000 1001				25 (CCD)	N.41.1-
CDS and PGA sample	e rate				28 (Video)	MHz
CDS full-scale input s	pan	Single-ended input			1	V
Input capacitance of 0	Input capacitance of CDS			4		pF
Minimum PGA gain				0		dB
Maximum DCA asia	CCD			36		40
Maximum PGA gain	Video			12		dB
PGA gain resolution				0.047		dB
PGA programming-co	de resolution	10-bit monotonic gain control		10	·	Bits

user digital-to-analog converter (DAC)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
	DAC resolution			8		Bits
INL	Integral nonlinearity			±1		LSB
DNL	Differential nonlinearity			±0.5		LSB
	Output voltage range		0		AVDD	V
	Output settling time	10-pF external load, settle to 1 mV		4		μs



electrical characteristics over recommended operating free-air temperature range, T_A = 25°C, AVDD = DVDD = 3 V, ADCCLK = 25 MHz (unless otherwise noted) (continued)

reference voltages

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Internal bandgap-voltage reference		1.43	1.50	1.58	V
Temperature coefficient			100		ppm/°C
Voltage-reference noise			0.5		LSB
ADC Ref+	Externally decoupled		2		V
ADC Ref-	Externally decoupled	_	1	·	V

digital specifications

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
Logic Inputs								
lн	High-level input current	DVDD 0.V	-10		10	•		
I _Ι L	Low-level input current	DVDD = 3 V	-10		10	μΑ		
Ci	Input capacitance			5		pF		
Logic C	Outputs							
Vон	High-level output voltage	$I_{OH} = 50 \mu A$, DIVDD = 3 V	DIVDD-0.4			V		
VOL	Low-level output voltage	$I_{OL} = 50 \mu\text{A}, \qquad \text{DIVDD} = 3 \text{V}$	0.4			V		
loz	High-impedance-state output current			±10		μΑ		
CO	Output capacitance			5		pF		

key timing requirements

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tSRW	SR pulse width	Measured at 50% of pulse height, recommend to use 1/4 of ADCCLK cycle	10			ns
tsvw	SV pulse width	Measured at 50% of pulse height, recommend to use 1/4 of ADCCLK cycle	10			ns
t _{SRD}	Delay between the SR rising edge (SR active low) and the actual sampling instant	Measured at 50% of pulse height		5		ns
tSVD	Delay between the SV falling edge (SV active low) and the actual instant of sampling the video signal	Measured at 50% of pulse height		8		ns
tADC_SV	Delay between the SV falling edge (SV active low) and the ADCCLK rising edge	Measured at 50% of pulse height	10			ns
tOD	ADCCLK-to-output data delay	Measured at 50% of pulse height		6		ns
	Maximum internal delay for SR, SV, and ADCCLK timing signals	With 16 programmable delay steps		7.5		ns
	SR, SV, and ADCCLK delay resolution			0.5		ns
tCSF	CS falling edge to SCLK rising edge when SCKP = 1, or CS falling edge to SCLK falling edge when SCKP = 0	Measured at 50% of pulse height	0			ns
tCSR	SCLK falling edge to CS rising edge when SCKP = 1, or SCLK falling edge to CS falling edge when SCKP = 0	Measured at 50% of pulse height	5			ns

NOTE: tSRD, tSVD, and tADC_SV minimum requirements are measured while the registers for internal delay are programmed to 0.



TYPICAL CHARACTERISTICS

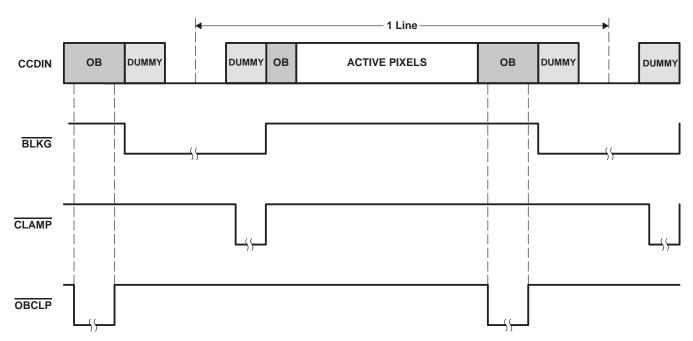


Figure 1. CCD Horizontal Synchronization Timing Diagram

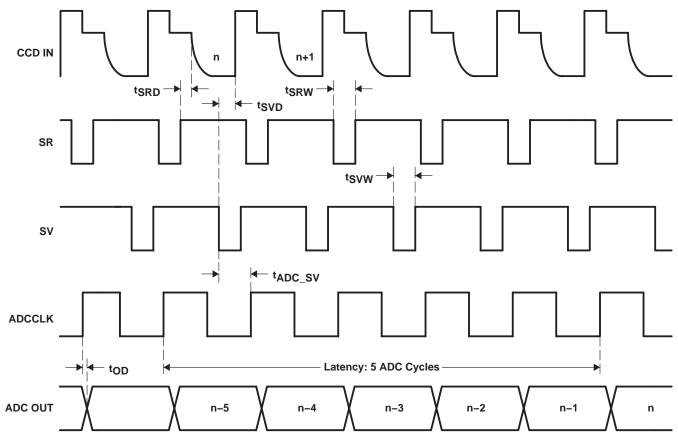
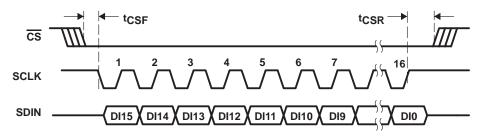


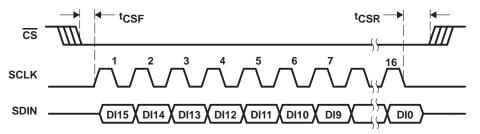
Figure 2. CCD Pixel Synchronization Timing Diagram



TYPICAL CHARACTERISTICS



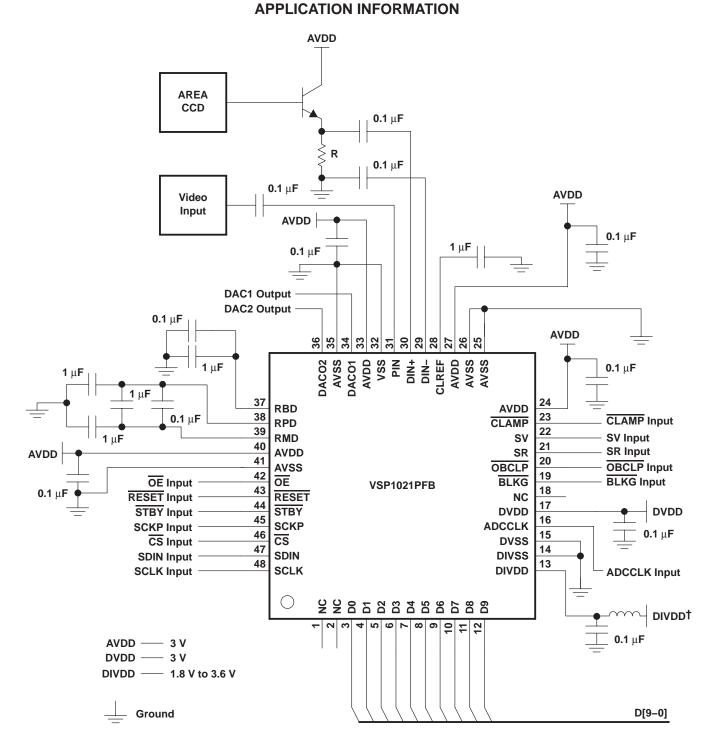
SCKP Terminal Is Pulled Low



SCKP Terminal Is Pulled High

Figure 3. Serial Interface Timing Diagram





 $\ensuremath{^\dagger}\xspace$ DIVDD is recommended to have a ferrite bead to filter the power transients.

NOTE: All analog outputs should be buffered if the load is resistive or if the load is capacitive with more than 2 pF loading. The decoupling capacitors for the power supplies must be placed as close as possible to these terminals.

Figure 4. Typical Application Connection



REGISTER DEFINITION

serial input data format

	DI15	DI14	DI13	DI12	DI11	DI10	DI9	DI8	DI7	DI6	DI5	DI4	DI3	DI2	DI1	DI0
ſ	Χ	X	А3	A2	A1	A0	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0

А3	A2	A1	A0		D9-D0
0	0	0	0	Control register 1	10-bit data to be written into the selected register
0	0	0	1	PGA gain register	
0	0	1	0	User DAC1 register	
0	0	1	1	User DAC2 register	
0	1	0	0	SR/SV delay	
0	1	0	1	Optical-black Vb setup register	
0	1	1	0	Control register 2	

control register 1 format (00H)

D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
STBY	PDD2	PDD1	DACD	Х	Х	Х	PSVR	Х	RTSY

control register 1 description

BIT	NAME	DESCRIPTION
D9	STBY	Device global power-down control: 1 = Standby 0 = Active (default)
D8	PDD2	Power down the user DAC2: 0 = Active (default) 1 = Standby
D7	PDD1	Power down the user DAC1: 0 = Active (default) 1 = Standby
D6	DACD	Sustain the user DACs in global standby 0 = User DACs are in standby during global standby (default) 1 = User DACs are not in standby during global standby
D5	Х	Reserved
D4	Х	Reserved
D3	Х	Reserved
D2	PSVR	This bit sets the polarity of the SV/SR. 0 = SV and SR are active low (default) 1 = SV and SR are active high
D1	Х	Reserved
D0	RTSY	Writing 1 to this bit resets the entire system to the default settings (active high).

Default = 00 0000 0000



REGISTER DEFINITION

PGA register format (01H)

	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
ſ	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0

Default PGA gain = 00 0000 0000 (0 dB)

NOTE: The gain-code range for CCD mode is 0–767, which covers the 0-dB to 36-dB range in 0.047-dB steps. Users must employ this code range. The gain stays at 36 dB when the code range is 768 to 1023. For the video mode, the gain code range is 256–512, which covers the 0-dB to 12-dB range in 0.047-dB steps. Users must employ a 256–512 code range for the video mode. In video mode, the gain code 0–255 must not be used. In video mode, the gain range is from 12 dB to 24 dB for the gain code range of 513 to 767; however, the offset might be too large for this gain range.

user DAC1 and DAC2 registers format (02H and 03H)

	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
ſ	Χ	Х	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0

Default user DAC register value = 00 0000 0000

NOTE: The DAC1 and DAC2 codes range from 0 to 255, which covers the 0-to-AVDD output voltages at DACO1 and DACO2 output terminals with linear correspondence.

SV/SR delay register format (04H)

	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
ſ	Χ	Х	SRL3	SRL2	SRL1	SRL0	SVL3	SVL2	SVL1	SVL0

SV/SR delay register description

BIT	NAME					DESCRIPTION				
D9-D8	Х	Reserv	Reserved							
D7-D4	SRL3-SRL0	These find SRL3 0 0 0	our bits se SRL2 0 0	t the interr SRL1 0 0 : :	nal SR dela SRL0 0 1	y. Set D7–D4 to 0 in video mode. Typical internal delay 0 ns (default) 0.5 ns				
D3-D0	SVL3-SVL0	These f SVL3 0 0	our bits se SVL2 0 0	t the interr SVL1 0 0 : :	nal SV dela SVL0 0 1	y. Set D3–D0 to 0 in video mode. Typical internal delay 0 ns (default) 0.5 ns				

Default SV/SR delay register value = 00 0000 0000



REGISTER DEFINITION

optical black Vb setup register format (05H)

	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
ſ	Х	Х	Х	Х	Х	NOB	VB3	VB2	VB1	VB0

optical black Vb setup register description

X NOB	Reserved This bit control 0 = OB out			e Vb setting and it is always 0.	
NOB				a Vh satting and it is always 0	
	1 = OB ou	put correspo	•	,	
VB3-VB0	VB3 VB2 0 0 0 0	2 VB1 0 0 :	VB0 0 1	OB output (when NOB = 1) 20 (default) 21	
/B	3-VB0	3–VB0 VB3 VB2 0 0	3-VB0	3-VB0	0 0 0 0 20 (default)

Default optical black Vb setup register value = 00 0000 0000

NOTE: If NOB (D4) is set to 0, VB3-VB0 (D3-D0) has no effect. The output OB is 0.

If NOB is set to 1, the output OB is defined by VB3-VB0, and ranges from 20 LSB to 35 LSB.

control register 2 format (06H)

D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
ADL3	ADL2	ADL1	ADL0	Х	Х	Х	GNDV	MOD	Х

control register 2 description

BIT	NAME					DESCRIPTION					
D9-D6	ADL3-ADL0	These for ADL3 0 0	ADL2 0 0	0 0 0 ns (default)							
D5 D0		7									
D5-D3	Х	Reserve	ed								
D2	GNDV	0 = 0	No short (d	efault)	hort the vio	deo terminal (PIN) to ground (VSS) internally. nd (VSS)					
D1	MOD	0 = 0	This bit defines the mode of the input. 0 = CCD mode (default) 1 = Video mode								
D0	Х	Reserve	d. Always	program t	his bit to 0						

Default register value = 00 0000 0000



PRINCIPLES OF OPERATION

CDS/PGA signal processor

In a CCD imaging system, the output from the CCD sensor is differentially fed to the correlated double sampler (CDS) of the VSP1021 device. The CCD signal is sampled and held during the reset reference interval and the video signal interval. By subtracting the two resulting voltage levels, the CDS removes low-frequency noise from the output of the CCD sensor and obtains the voltage difference between the CCD reference level and the video level of each pixel. Two sample/hold control pulses (SR and SV) are required to perform the CDS function.

The CCD output is capacitively coupled to the VSP1021 device. The CLAMP input clamps the ac-coupling capacitor to establish the proper dc bias during the dummy pixel interval. The bias at the input to the VSP1021 device is set to 1.2 V. Normally, CLAMP is applied at the sensor's line rate. A capacitor with a value ten times larger than that of the input ac-coupling capacitor should be connected between terminal 28 (CLREF) and AVSS.

The signal is sent to the PGA after completing the CDS function. The PGA gain can be adjusted from 0 to 36 dB by programming the internal gain register via the serial port. The PGA is digitally controlled with 10-bit resolution on a linear dB scale, resulting in a 0.047-dB gain step. The gain can be expressed by the following equation:

Gain = PGA code × 0.047 dB

where the PGA code has a range of 0 to 767.

For example, if the PGA code = 128, then the PGA Gain = 6 dB (a gain of 2).

In CCD mode, users must use the 0–767 range for the PGA-gain code. The gain stays at 36 dB when the code is from 768 to 1023.

video-mode operation

The VSP1021 device also provides an analog video processing channel that consists of an input clamp, a PGA, and an ADC. Setting bit D1 (MOD) to 1 in control register 2 enables the video channel. The video signal must be connected to terminal 31 (PIN) via a 0.1-μF capacitor as shown in Figure 4.

The video input has its own clamp circuit operated automatically. Around 60 LSB is added to balance the offset of the output with zero input.

The PGA gain in the video mode can be adjusted from 0 to 12 dB by programming the internal gain register via the serial port. The PGA is digitally controlled with 10-bit resolution on a linear dB scale, resulting in a 0.047-dB gain step. The gain can be expressed by the following equation,

Gain = (PGA code-256) \times 0.047 dB

where the PGA code has a range of 256 to 512.

For the video mode, users must utilize the 256 to 512 range for the PGA gain code. The gain code 0–255 must not be used, and the gain range is from 12 dB to 24 dB for the gain code range of 513 to 767; however, the offset might be too large for this gain range.

In the video mode, the internal SR and SV delays need to be set to 0.



PRINCIPLES OF OPERATION

internal timing

As previously explained, the SR and SV signals are required to operate the CDS. Users need to synchronize the SR and SV clocks with the CCD signal waveform. The ADCCLK signal fine tunes the databus output in relation to the CDS timing to achieve optimal performance (see Figure 2).

The CLAMP signal activates the clamping circuit for the input signal. The OBCLP signal activates the optical-black calibration, and the active portion (the low pulse) of this signal must be within the optical-black period of the CCD (see Figure 1).

ADC

The ADC employs a pipelined architecture to achieve high throughput and low-power consumption. Fully-differential implementation and digital-error correction ensure 10-bit resolution.

The latency of the ADC data output is the default five ADCCLK cycles as shown in Figure 2. Pulling terminal 42 (OE) high puts the ADC output in high impedance.

automatic optical black calibration

In the VSP1021 device, the optical black and the system channel offset corrections are performed by an automatic analog-feedback loop. During the optical-black-calibration interval (OBCLP = low) of each line, the optical-black pixels plus the channel offset are sampled and compared with the desired black level specified in the optical-black Vb setup register. The difference is then integrated and added to incoming pixel data at the PGA input. This analog feedback loop will calibrate the PGA output to the desired black pixel level, which can be programmed to either zero or from 20 LSBs to 35 LSBs in 1-LSB/step resolution via the serial port. The OB calibration settles within approximately 1000 OB pixels in order to avoid line noise.

input blanking function

During the blanking period of CCD operation, <u>large</u> input transients may occur at the VSP1021 input, making the ADC output unpredictable. Activating the <u>BLKG</u> pulse during this period will ensure a digital code of zero at the ADC output.

user DACs

The VSP1021 device includes two user DACs that can be utilized for external analog settings. The output voltage of each DAC can be independently set and has a range of 0 V to the supply voltage, with an 8-bit resolution. When the user DACs are not used in a camera system, they can be put in the standby mode by programming control bits in control register 1. The following table defines the status of the user DACs.

SOFTWARE/HARDWARE GLOBAL STANDBY	PDD1/PDD2	DACD	STATUS OF DAC1/DAC2
Active	0	Х	Active
Active	1	х	Standby
Standby	0	0	Standby
Standby	0	1	Active
Standby	1	Х	Standby

NOTE:

The hardware global standby is set by pulling down terminal 44 (STBY) of the VSP1021 device. The software global standby is controlled by setting bit D9 (STBY) in control register 1 to 1.



PRINCIPLES OF OPERATION

three-wire serial interface

A simple three-wire (SCLK, SDIN, and \overline{CS}) serial interface is provided to allow writing to the internal registers of the VSP1021 device. Serial clock SCLK can be run at a maximum speed of 40 MHz. Serial data SDIN is 16 bits long. After 2 leading null bits, there are 4 address bits for which the internal register is to be updated; the following 10 bits are the data to be written to the register. Terminal 46 (\overline{CS}) must be held low to enable the serial port. The data transfer is initiated by the incoming SCLK after \overline{CS} falls. Figure 3 shows the detailed timing for the serial interface.

The SCLK polarity is selected by pulling terminal 45 (SCKP) either high or low.

device reset

The device is not under the default configuration after power on. The registers are set to the default value by a reset. When terminal 43 (RESET) is pulled low, all internal registers are set to their default values. In addition, the VSP1021 device has a software-reset function that resets the device when writing a control bit to control register 1.

See the register definition section for the register default values.

power-down mode (standby)

The VSP1021 device implements both hardware and software power-down modes. Pulling terminal 44 (STBY) low puts the device in the low-power standby mode. The total power drops to about 1 mW. Setting a power-down control bit in the control register can also activate the power-down mode. Users can still program all internal registers during the power-down mode.

power supply

The VSP1021 device has several power-supply terminals. Each major internal analog block has a dedicated AVDD supply terminal. All internal digital circuitry is powered by DVDD. Both AVDD and DVDD are 3 V nominal.

Terminals 13 (DIVDD) and 14 (DIVSS) supply power to the output digital driver (D9–D0). DIVDD is independent of DVDD and can be operated from 1.8 V to 3.6 V. This allows the outputs to interface with digital ASICs requiring different supply voltages.

grounding and decoupling

General practices should apply to the printed-circuit-board (PCB) design to limit high-frequency transients and noise that feed back into the supply and reference lines. This requires sufficient bypass of the supply and reference terminals. In the case of power-supply decoupling, 0.1-µF ceramic chip capacitors are adequate to keep the impedance low over a wide frequency range. Recommended external decoupling for the three voltage-reference terminals is shown in Figure 4. Since the effectiveness of the decoupling capacitors depends largely on the proximity to the individual supply terminal, they must be placed as close as possible to these terminals. An inductor is recommended for the DIVDD power supply (see Figure 4). Common ground level is also recommended.

voltage references

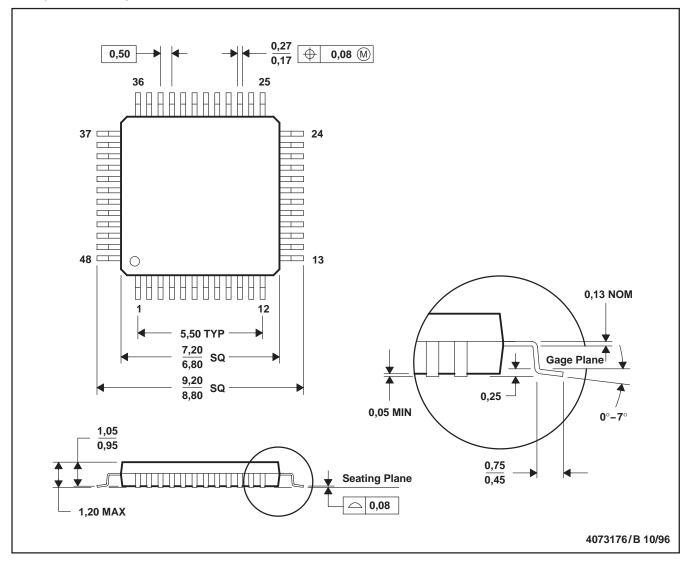
An internal precision voltage reference of 1.5 V nominal is provided. This reference voltage generates the ADC Ref– voltage of 1 V and Ref+ of 2 V. It also generates the internal clamp voltage. All internally-generated voltages are fixed values and cannot be adjusted. Terminals 37 (RBD), 38 (RPD), and 39 (RMD) must not be used to drive any loads.



MECHANICAL DATA

PFB (S-PQFP-G48)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-026





PACKAGE OPTION ADDENDUM

7-May-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins F	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
VSP1021PFB	ACTIVE	TQFP	PFB	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
VSP1021PFBG4	ACTIVE	TQFP	PFB	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PFB (S-PQFP-G48)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-026

PFB (S-PQFP-G48)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products Amplifiers amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated